

Abstract of the Disclosure

An interposer-based semiconductor package (40) having at least one semiconductor die (21) attached to one side thereof also has, prior to placement on a printed wiring board (61), an underfill material (31) disposed at least partially thereon. Depending upon the embodiment, the underfill material (31) may initially cover interface electrodes (12) on the interposer (11). Such material (31) can be selectively removed to partially expose the interface electrodes (12). In other embodiments, apertures (101) can be left in the underfill material (31) during deposition, or formed after the underfill material (31) has been deposited, and the interface electrodes (12) subsequently formed in the apertures (101). Deposition of the underfill material (31) can be done with a single interposer-based package (40) or simultaneously with a plurality of such packages. Once deposited, the underfill material can be processed to render it relatively stable and substantially non-tacky. So processed, the package can be easily handled.